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Renesas Electronics website: <http://www.renesas.com>

April 1st, 2010
Renesas Electronics Corporation

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Errata

[Document Name]

μ PD17072, 17073 DATA SHEET

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Microcomputer Engineering Department Semiconductor Solution Engineering Division NEC Corporation

[Description]

p.219 : Modify the description of **Table 25-1. Soldering Conditions for Surface-Mount Type.**

<Error>

(1) μ PD17072GB-xxx-1A7:56-pin plastic QFP (10 × 10 mm, 0.65-mm pitch)

μ PD17073GB-xxx-1A7:56-pin plastic QFP (10 × 10 mm, 0.65-mm pitch)

Soldering method	Soldering Condition	Symbol of Recommended Soldering
Infrared Reflow	Package peak temperature: 235 °C, Time: 30 seconds MAX. (210 °C MIN.) Number of times: 2 MAX.	IR35-00-2
VPS	Package peak temperature: 215 °C, Time: 40 seconds MAX. (210 °C MIN.) Number of times: 2 MAX.	VP15-00-2
Wave soldering	Soldering bath temperature: 260 °C MAX., Time: 10 seconds MAX., Number of times: 1, Preheating temperature: 120 °C MAX. (package surface temperature)	WS60-00-1
Pin partial heating	Pin temperature: 300 °C MAX., Time: 3 seconds MAX. (per side of device)	—

Caution Do not use two or more soldering methods in combination (except pin partial heating) .

<Correct>

(1) μ PD17072GB-xxx-1A7:56-pin plastic QFP (10 × 10 mm, 0.65-mm pitch)

μ PD17073GB-xxx-1A7:56-pin plastic QFP (10 × 10 mm, 0.65-mm pitch)

Soldering method	Soldering Condition	Symbol of Recommended Soldering
Infrared Reflow	Package peak temperature: 235 °C, Time: 30 seconds MAX. (210 °C MIN.) Number of times: 2 MAX., Number of days : 3 ^{Note} (after that, prebaking at 125 °C for 10 hours is necessary) <<Caution>> (1) Start second reflow after device temperature that was raised by first reflow has cooled down to room temperature. (2) Do not clean flux with water after first reflow.	IR35-203-2
VPS	Package peak temperature: 215 °C, Time: 40 seconds MAX. (210 °C MIN.) Number of times: 2 MAX., Number of days : 3 ^{Note} (after that, prebaking at 125 °C for 10 hours is necessary) <<Caution>> (1) Start second reflow after device temperature that was raised by first reflow has cooled down to room temperature. (2) Do not clean flux with water after first reflow.	VP15-203-2
Wave soldering	Soldering bath temperature: 260 °C MAX., Time: 10 seconds MAX., Number of times: 1, Preheating temperature: 120 °C MAX. (package surface temperature), Number of days : 3 ^{Note} (after that, prebaking at 125 °C for 10 hours is necessary)	WS60-203-1
Pin partial heating	Pin temperature: 300 °C MAX., Time: 3 seconds MAX. (per side of device)	—

Note The number of days for which the device can be stored after the dry pack is opened, at 25 °C, 65 %RH MAX.

Caution Do not use two or more soldering methods in combination (except pin partial heating) .